

Parker Chomerics CHO-BOND SV713 Conductive Epoxy

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy, Electrically Conductive

Material Notes:

CHO-BOND® 700 Series Adhesives for Microelectronics Packaging; these pure silver-filled epoxy pastes are designed to meet the demanding requirements of semiconductor and microelectronic packaging. They are one-component systems with a unique combination of excellent die shear strength, low coefficients of thermal expansion, ionic purity, and high thermal and electrical conductivities. Each offers and extended working life with viscosity and thixotropy suitable for both time/pressure and positive displacement dispensing methods.

CHO-BOND® SV713 is especially well suited for temperature-sensitive, high performance applications. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-SV713-Conductive-Epoxy.php

Physical Properties	Metric	English	Comments
Specific Gravity	2.20 - 2.80 g/cc	2.20 - 2.80 g/cc	
Volatile Organic Compounds (VOC) Content	0.00 g/l	0.00 g/l	
Solubility in Water	0.00 %	0.00 %	Insoluble
Thickness	25.4 microns	1.00 mil	Recommended

Mechanical Properties	Metric	English	Comments
Shear Strength	6.89 MPa	1000 psi	Lap
	31.0 MPa	4500 psi	Die

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	150 °C	302 °F	
Minimum Service Temperature, Air	-45.0 °C	-49.0 °F	
Flash Point	>= 93.3 °C	>= 200 °F	

Component Elements Properties	Metric	English	Comments
Silver, Ag	60 - 85 %	60 - 85 %	

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00070 ohm-cm	<= 0.00070 ohm-cm	

Processing Properties	Metric	English	Comments
	30.0 min	0.500 hour	

Cure Time Processing Properties	Metric @ Temperature 150 °C	English @ Temperature 302 °F	Comments
	60.0 min	1.00 hour	
	@Temperature 125 °C	@Temperature 257 °F	
Shelf Life	12.0 Month	12.0 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Alkyl Glycidyl Ether wt. % Max	5	
Amine Compound Proprietary wt. % Max	10	
Binder	Epoxy	
Consistency	Thixotropic Paste	
Epoxy Resin, wt %	15 - 25	
Filler	Ag	
Mix Ratio	1-part	
o-Cresyl glycidyle ether wt. % Max	5	
Working Life	3 weeks	

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